L Number	Hits	Search Text	DB	Time st
1	20324	flip NEAR chip	USPAT;	2004/02
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	2004/04
2	20325	flip NEAR chip\$1	USPAT;	2004/02
			US-PGPUB;	
1			ЕРО; ЛРО;	
			DERWENT;	
	100	(G' NT) AD 1' 61\ 1 (/1' NT) AD 1 164\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \	IBM_TDB USPAT;	2004/02
3	120	(flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	US-PGPUB;	2004/02
		open\$3 hole\$1))	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	10	(flin NEAD shings) and ((dia NEAD nodga) WEEL (consequited hallow	USPAT;	2004/02
4	19	(flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1) WITH bump\$1)	US-PGPUB;	2004/02
		openas noteat) with outlipat)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	28	   ("3648002"   "3832632"   "3971610"   "4288841"   "4329642"	USPAT	2004/02
'	20	(3048002   3832032   3771010   4288641   4327042	051711	200 1702
		"4956605"   "5006792"   "5006796"   "5014161"   "5061192"		
		"5123850"   "5173451"   "5207585"   "5248262"   "5302891"		ļ
		"5329423"   "5358417"   "5453701"   "5475315"   "5489854"		
		"5493237"   "5633596"   "5656945").PN.		
6	93	((flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	USPAT;	2004/02
"	/3	open\$3 hole\$1))) and bump\$1	US-PGPUB;	
		openios notes ())) and outspox	ЕРО; ЛРО;	
			DERWENT;	
			IBM TDB	
7	74	(((flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	USPAT;	2004/02
'	, ,	open\$3 hole\$1))) and bump\$1) and (bond\$3 NEAR pad\$1)	US-PGPUB;	
			ЕРО; ЛРО;	İ
		·	DERWENT;	ŀ
			IBM_TDB	
8	53	(flip NEAR chip\$1) and ((lead NEAR frame) WITH (tie NEAR bar\$1))	USPAT;	2004/02
			US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
9	7	("5091341"   "5147821"   "5200809"   "5202288"   "5387554"	USPAT	2004/02
		"5442234"   "5570272").PN.	I TIOD A TO	2004/0
10	6	("3729573"   "4377548"   "4470786"   "4626185"   "4823234"	USPAT	2004/02
l		"4954307").PN.	LICDATE	2004/05
11	34	((die NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1) WITH	USPAT;	2004/02
		bump\$1)	US-PGPUB; EPO; JPO;	
			DERWENT:	
			IBM_TDB	
12	004	(die NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1)	USPAT;	2004/02
12	994	(uie reak paus4) witti (concavits nonow opens noies)	US-PGPUB;	2004/02
			EPO; JPO;	
			DERWENT;	
			IBM TDB	1
13	79	((die NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1)) and	USPAT;	2004/02
13	13	((lead NEAR frame) WITH (tie NEAR bar\$1))	US-PGPUB;	
		((load 1112 II IIIIII) 111111 (III 1112 II Outo 1))	EPO; JPO;	
			DERWENT;	
			IBM TDB	1
L	L		11/11/11/11	ــــــــــــــــــــــــــــــــــــــ

L Number	Hits	Search Text	DB	Time st
1	20324	flip NEAR chip	USPAT;	2004/02
	ŀ		US-PGPUB;	
			ЕРО; ЈРО;	
1			DERWENT;	
			IBM_TDB	
2	20325	flip NEAR chip\$1	USPAT;	2004/02
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	1
	ĺ		IBM_TDB	ł
3	120	(flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	USPAT;	2004/02
		open\$3 hole\$1))	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
4	19	(flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	USPAT;	2004/02
		open\$3 hole\$1) WITH bump\$1)	US-PGPUB;	ĺ
			ЕРО; ЈРО;	
			DERWENT;	
_			IBM_TDB	2004/06
5	28	("3648002"   "3832632"   "3971610"   "4288841"   "4329642"	USPAT	2004/02
		"4340860"   "4437718"   "4554505"   "4739257"   "4899107"		
		"4956605"   "5006792"   "5006796"   "5014161"   "5061192"		
		"5123850"   "5173451"   "5207585"   "5248262"   "5302891"		
		"5329423"   "5358417"   "5453701"   "5475315"   "5489854"		
	0.2	"5493237"   "5633596"   "5656945").PN.	USPAT;	2004/02
6	93	((flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	US-PGPUB;	2004/02
		open\$3 hole\$1))) and bump\$1	EPO; JPO;	
			DERWENT;	
			IBM TDB	
7	74	(((flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	USPAT;	2004/02
7	'4	open\$3 hole\$1))) and bump\$1) and (bond\$3 NEAR pad\$1)	US-PGPUB;	2004/02
		opens notes ()) and bumps () and (bolicus 1122 it page)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	53	(flip NEAR chip\$1) and ((lead NEAR frame) WITH (tie NEAR bar\$1))	USPAT;	2004/02
		(inp 112) at ompor) and ((1888 112) at name) ************************************	US-PGPUB;	1
	1		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	7	("5091341"   "5147821"   "5200809"   "5202288"   "5387554"	USPAT	2004/02
		"5442234"   "5570272").PN.		
10	6	("3729573"   "4377548"   "4470786"   "4626185"   "4823234"	USPAT	2004/02
1		"4954307").PN.		-
11	34	((die NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1) WITH	USPAT;	2004/02
		bump\$1)	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
12	994	(die NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1)	USPAT;	2004/02
			US-PGPUB;	
			EPO; JPO;	,
			DERWENT;	
1	_		IBM_TDB	2004/01
13	79	((die NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1)) and	USPAT;	2004/02
i		((lead NEAR frame) WITH (tie NEAR bar\$1))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	<u> </u>		IBM_TDB	L

14	18	thermal\$2 NEAR conduct\$3 NEAR bump\$1	USPAT;	2004/02
• •	"		US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM TDB	
15	2	("6331451").PN.	USPĀT;	2004/02
"	_	( •••• ):= = ::	US-PGPUB;	
]			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
16	0	("2and((heatNEARspreader)WITHchip)").PN.	USPAT;	2004/02
'		( 2000 ( 1000 100 100 100 100 100 100 100 1	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
	ļ		IBM TDB	
17	303	(flip NEAR chip\$1) and ((heat NEAR spreader) WITH chip)	USPAT;	2004/02
*′	303	(mp 1121 mt ompor) and ((near 122 mt sprouder) ************************************	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM TDB	
18	0	((flip NEAR chip\$1) and ((heat NEAR spreader) WITH chip)) and ((die	USPAT;	2004/02
10	"	NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1))	US-PGPUB;	
!		TALFITE padd 4) TTTTT (contest tids notion openess noted 1))	ЕРО; ЛРО;	
			DERWENT;	
			IBM TDB	
19	0	((flip NEAR chip\$1) and ((heat NEAR spreader) WITH chip)) and	USPAT;	2004/02
19		((lead NEAR frame) WITH (tie NEAR bar\$1))	US-PGPUB;	200
		((lead IVEAR Hame) WITH (do IVEAR ball 1))	EPO; JPO;	
			DERWENT,	
	]		IBM TDB	
20	186	((flip NEAR chip\$1) and ((heat NEAR spreader) WITH chip)) and	USPAT;	2004/02
20	180	bump\$1	US-PGPUB;	20001
		oump#1	EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
21	77	(((flip NEAR chip\$1) and ((heat NEAR spreader) WITH chip)) and	USPAT;	2004/01
21	· · · ·	bump\$1) and (bond\$3 NEAR pad\$1)	US-PGPUB;	
	1	oumput) and (ounds) His he padut)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
22	0	(flip NEAR chip\$1) and (heat NEAR transmission NEAR (layer film))	USPAT;	2004/02
22		(inp iven in only in and thou iven in additional in the interior)	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
23	1	chip WITH (heat NEAR transmission NEAR (layer film))	USPAT;	2004/02
	1	and (want i'm to a manning of i i'm we (wa) as seen,))	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	l
24	7	chip and (heat NEAR transmission NEAR (layer film))	USPAT;	2004/02
1	,		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
25	0	(active NEAR surface NEAR chip) WITH (electrically NEAR	USPAT;	2004/02
=		connect\$3) WITH (tie NEAR bar\$1)	US-PGPUB;	
		,	ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
L	<del></del>	<u> </u>	1	<del></del>

27	7	(chip\$1 WITH (electrically NEAR connect\$3) WITH (tie NEAR bar\$1))	USPAT,	2004/02
		and active	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
28	3	(chip\$1 WITH (electrically NEAR connect\$3) WITH (tie NEAR bar\$1))	USPAT;	2004/02
	1	and (flip NEAR chip\$1)	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
29	3	(chip\$1 WITH (electrically NEAR connect\$3) WITH (tie NEAR bar\$1))	USPAT;	2004/02
		and ((flip NEAR chip\$1) and ((lead NEAR frame) WITH (tie NEAR	US-PGPUB;	
		bar\$1)))	ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
30	6	("4534105"   "5198886"   "5331203"   "5583370"   "5684330"	USPAT	2004/02
		"5821615").PN.		
26	47	chip\$1 WITH (electrically NEAR connect\$3) WITH (tie NEAR bar\$1)	USPAT;	2004/02
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	L